Topics

Papers are solicited in the following themes of interest:

- Power and/or high speed (microwave to THz devices) devices, modules, and systems
- Manufacturing processes, device design, modeling, physics, and reliability of power and/or high-speed devices
- Fundamental studies on doping, traps, interface states, and device reliability for power and/or high-speed switching devices
- Micro and mm-wave devices, such as PAs, LNAs, switches and mixers.
- Energy harvesting devices and circuits
- Tunable passives, SAW/BAW/MEMS RF devices, antenna arrays

New or trending areas include:

- Wide bandgap and ultra-wide bandgap semiconductors such as SiC, (Al)GaN, diamond, β-Ga2O3, BN
- Large $k^2$ piezoelectric material: LNO, LTO, AlN(Sc)...
- Power devices for applications for automotive and aviation to smart grid
- Device and circuits for 5G and 6G
- Antenna arrays and beam forming
- Extreme environment power and high-speed devices

Paper Submission

Submission deadline: July 11th
Single submission of final, four-page paper